

**IN THE CLAIMS:**

**Please revise the claims to read as follows:**

1. (Previously presented) A light emitting device comprising:

an insulating base having a plurality of electrical leads including positive and negative leads provided on top and bottom surfaces thereof, including a negative lead on said top surface and a negative lead on said bottom surface, each said negative lead comprising a common metal layer;

an LED chip array arranged on said negative lead on said top surface of said insulating base, said LED chip array being electrically connected to said positive and negative leads on said top surface of said insulating base;

a plurality of first metal connections configured to respectively interconnect said positive leads on said top and bottom surfaces of said insulating base; and

at least one second metal connection configured to interconnect said negative leads on said top and bottom surfaces of said insulating base, wherein for each said at least one second metal connection, one LED chip of said LED chip array is mounted directly thereon.

2. (Previously presented) The light emitting device according to claim 1, wherein:

said LED chip array comprises blue, green, and red LED chips,

the positive leads include blue, green, and red positive leads arranged at one side of said LED chip array,

the negative leads include a first common lead arranged at another side of said LED chip array and a second common lead arranged at said one side of said LED chip array,

said blue LED chip being connected to said blue positive lead and said second common

lead by bonding wires,

said green LED chip being connected to said green positive lead and said first common lead by bonding wires, and

said red LED chip being connected to said red positive lead by a bonding wire and to said first common lead by a direct contact with a bottom electrode thereof.

3. (Original) The light emitting device according to claim 1, wherein:

said LED chip array comprises blue, green and red LED chips having one arrangement selected from a first arrangement, a second arrangement and a third arrangement,

said first arrangement including a green LED chip, a red LED chip, a blue LED chip, a red LED chip and a green LED chip arranged in order in a predetermined direction,

said second arrangement including a red LED chip, a green LED chip, a blue LED chip, a green LED chip and a red LED chip arranged in order in said predetermined direction, and

said third arrangement including a red LED chip, a blue LED chip, a green LED chip, a blue LED chip and a red LED chip arranged in order in said predetermined direction.

4. (Currently amended) A light emitting device comprising:

an insulating base having an upper surface and a lower surface;

a metal layer provided on the upper surface and the lower surface of the insulating base;

a plurality of light emitting elements arranged on the metal layer provided on the upper surface of the insulating base; and

a metal connection that connects the metal layers to each other at a position substantially directly ~~over~~ beneath a location where at least one of the plurality of light emitting elements is disposed.

5. (Previously presented) The light emitting device according to claim 4, wherein the metal connection comprises a through-hole plating.

6. (Previously presented) The light emitting device according to claim 5, wherein the through-hole plating has a hollow portion filled with metal.

7. (Original) The light emitting device according to claim 4, wherein:

the plurality of light emitting elements comprises a first light emitting element configured to emit light at a predetermined heat amount and a second light emitting element configured to emit light at a lower heat amount than the predetermined heat amount, and

the metal connection connects the metal layers to each other at a position where the first light emitting element has been disposed.

8. (Original) The light emitting device according to claim 4, wherein:

the plurality of light emitting elements comprises one blue light emitting element, one or more green light emitting elements, and two or more red light emitting elements.

9. (Original) The light emitting device according to claim 4, wherein:

the plurality of light emitting elements comprises one blue light emitting element, two

green light emitting elements, and two red light emitting elements.

10. (Previously presented) A light emitting device, comprising:

a substrate comprising a plurality of leads provided on an insulating base;

a plurality of light emitting elements arranged substantially on a single base line along a surface of the substrate in a predetermined direction, wherein all light emitting elements mounted on said substrate are arranged on said single base line; and

a plurality of bonding wires configured to connect the plurality of light emitting elements to the plurality of leads in the predetermined direction or on one side relative to the base line.

11. (Original) The light emitting device according to claim 10, wherein the substrate comprises a reflection case having an opening provided on a side thereof on which the plurality of light emitting elements are arranged and a seal member comprising a light transparent material configured to fill the opening in the reflection case to seal the plurality of light emitting elements in the reflection case, said opening configured to surround the plurality of light emitting elements and extending toward the side where the plurality of bonding wires are provided.

12. (Original) The light emitting device according to claim 10, wherein:

the substrate comprises a reflection case having an opening provided on its side where the plurality of light emitting elements are arranged, so as to surround the plurality of light emitting elements and be positioned toward the plurality of bonding wires; and

a seal member comprising a light transparent material filled into the opening in the reflection case which seals the plurality of light emitting elements.

13. (Previously presented) The light emitting device according to claim 10, wherein the substrate comprises a printed circuit board with the plurality of leads provided on the insulating base by a circuit printing method.

14. (Original) The light emitting device according to claim 10, wherein the substrate has a lead frame structure formed by placing a lead frame corresponding to the plurality of leads within a mold and pouring an insulating material into the mold.

15. (Original) The light emitting device according to claim 10, wherein:

the plurality of light emitting elements comprises one blue light emitting element, one or more green light emitting elements, and two or more red light emitting elements.

16. (Original) The light emitting device according to claim 10, wherein:

the plurality of light emitting elements comprises one blue light emitting element, two green light emitting elements, and two red light emitting elements.

17. (Currently amended) A light emitting device comprising:

a first metal layer provided on an upper surface of an insulating base;

a second metal layer provided on a lower surface of the insulating base;

a plurality of light emitting elements arranged along a base line on a surface of the first

metal layer in a predetermined direction; and

a metal connection configured to connect the first and second layers to one another, said metal connection located at a position substantially directly ~~over~~ beneath a location where a predetermined light emitting element of the plurality of light emitting elements is disposed.

18. (Original) The light emitting device according to claim 17, wherein the substrate comprises a reflection case having an opening provided on a side thereof on which the plurality of light emitting elements are arranged and a seal member comprising a light transparent material configured to fill the opening in the reflection case to seal the array of light emitting elements in the reflection case, said opening being configured to surround the plurality of light emitting elements and be positioned eccentrically toward the plurality of bonding elements.

19. (Original) The light emitting device according to claim 17, wherein the plurality of light emitting elements comprises one blue light emitting element, one or more green light emitting elements, and two or more red light emitting elements.

20. (Original) The light emitting device according to claim 17, wherein the plurality of light emitting elements comprises one blue light emitting element, two green light emitting elements, and two red light emitting elements.

21. (Previously presented) A light emitting device for driving a plurality of LED chips disposed in an array to emit a mixed light including lights emitted from the plurality of LED

chips, said light emitting device comprising:

an LED chip connection lead provided on an upper surface of an insulating base;  
a power supply connection lead provided on a lower surface of the insulating base; and  
a link lead configured to connect the LED chip connection lead to the power supply connection lead between the upper and lower surfaces of the insulating base,  
wherein the LED chip connection lead comprises a plurality of separate leads connected respectively to the plurality of LED chips and a common lead connected to the plurality of LED chips by a common connection, the common lead being loaded with the plurality of LED chips and configured to absorb heat generated from the plurality of LED chips,  
a location of each LED chip on said common lead being based on a relative amount of heat dissipated by each LED chip in said plurality of LED chips.

22. (Previously presented) The light emitting device according to claim 21, wherein:

the common lead has an elongated region having predetermined width and length sufficient to be loaded with the plurality of LED chips,

the plurality of LED chips comprises a first plurality of LED chips having positive and negative electrodes on a light emitting face thereof and a second plurality of LED chips having positive and negative electrodes on a light emitting face and a substrate side thereof, and

the first and second pluralities of LED chips are alternatively loaded into the elongated region of the common lead.

23. (Original) The light emitting device according to claim 22, wherein

the link lead comprises a plurality of through-hole platings configured to connect the common lead to the power supply connection lead at a position adjacent to and below the plurality of first LED chips.

24. (Original) The light emitting device according to claim 21, wherein

the link lead comprises a plurality of through-hole platings configured to connect the plurality of separate leads to the power supply connection lead.

25. (Previously presented) The light emitting device according to claim 21, wherein

the power supply connection lead comprises a common lead, which is connected to one of a power supply and a ground and a plurality of separate leads connected to the other one of the ground and the power supply.

26. (Previously presented) A light emitting device comprising:

- a first metal layer provided on an upper surface of an insulating base;
- a second metal layer provided on a lower surface of the insulating base;
- a plurality of light emitting elements arranged along a base line on a surface of the first metal layer in a predetermined direction;
- a metal connection configured to connect the first and second layers to one another, said metal connection located at a position where a predetermined light emitting element of the plurality of light emitting elements is disposed; and
- at least one bonding wire that electrically connects at least one of said plurality of light



emitting elements to said first metal layer.

27. (Previously presented) A light emitting device comprising:

- a first metal layer provided on an upper surface of an insulating base;
  - a second metal layer provided on a lower surface of the insulating base;
  - a plurality of light emitting elements arranged along a base line on a surface of the first metal layer in a predetermined direction;
  - a metal connection configured to connect the first and second layers to one another, said metal connection located at a position where a predetermined light emitting element of the plurality of light emitting elements is disposed;
  - a plurality of metal contacts on said upper surface on one side relative to said base line;
- and
- a corresponding plurality of bonding wires that respectively connect said metal contacts to corresponding said light emitting elements.

28. (Previously presented) A light emitting device comprising:

- a base;
- a first metal pattern formed on a top surface of said base as a single region of metal;
- a plurality of light emitting chips mounted on said first metal pattern;
- a second metal pattern on said top surface, said second pattern having a number of regions corresponding in number to said plurality of light emitting chips;
- a plurality of bonding wires, each electrically interconnecting one of said regions of said second metal pattern to one of said plurality of light emitting chips;

a third metal pattern formed on a bottom surface of said base as a single region of metal; and

a fourth metal pattern on said bottom surface, said fourth pattern having a plurality of regions corresponding in number to said plurality of light emitting chips,

wherein said first metal pattern and said third metal pattern are electrically interconnected by at least one metalized through-hole and each said region in said second metal pattern is electrically interconnected to a corresponding region in said fourth metal pattern by a metalized through-hole.

29. (Previously presented) The light emitting device of claim 28, wherein each said at least one metalized through-hole interconnecting said first metal pattern and said third metal pattern is located directly below one of said plurality of light emitting chips.

30. (Previously presented) The light emitting device of claim 28, wherein said first metal pattern comprises one of a "C" shape, an "H" shape, and an "L" shape.

31. (Previously presented) A light emitting device, comprising:

lead patterns provided on top and bottom surfaces of an insulating base;

a lead for connecting the lead patterns; and

a light emitting diode provided substantially directly over a location where the lead is positioned, the light emitting diode having first and second electrodes, one of which being connected to one of the lead patterns.